

## Silicon Carbide Power Schottky Diode

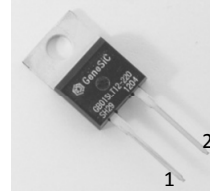
$V_{RRM}$	=	1200 V
$V_F$	=	1.6 V
$I_F$	=	1 A
$Q_C$	=	13 nC

### Features

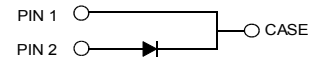
- 1200 V Schottky rectifier
- 175 °C maximum operating temperature
- Temperature independent switching behavior
- Superior surge current capability
- Positive temperature coefficient of  $V_F$
- Extremely fast switching speeds
- Superior figure of merit  $Q_C/I_F$

### Package

- RoHS Compliant



TO – 220AC



### Advantages

- Improved circuit efficiency (Lower overall cost)
- Low switching losses
- Ease of paralleling devices without thermal runaway
- Smaller heat sink requirements
- Low reverse recovery current
- Low device capacitance
- Low reverse leakage current at operating temperature

### Applications

- Power Factor Correction (PFC)
- Switched-Mode Power Supply (SMPS)
- Solar Inverters
- Wind Turbine Inverters
- Motor Drives
- Induction Heating
- Uninterruptible Power Supply (UPS)
- High Voltage Multipliers

### Maximum Ratings at $T_j = 175\text{ °C}$ , unless otherwise specified

Parameter	Symbol	Conditions	Values	Unit
Repetitive peak reverse voltage	$V_{RRM}$		1200	V
Continuous forward current	$I_F$	$T_C \leq 160\text{ °C}$	1	A
RMS forward current	$I_{F(RMS)}$	$T_C \leq 160\text{ °C}$	2	A
Surge non-repetitive forward current, Half Sine Wave	$I_{F,SM}$	$T_C = 25\text{ °C}$ , $t_p = 10\text{ ms}$	10	A
		$T_C = 160\text{ °C}$ , $t_p = 10\text{ ms}$	8	
Non-repetitive peak forward current	$I_{F,max}$	$T_C = 25\text{ °C}$ , $t_p = 10\text{ }\mu\text{s}$	65	A
$i^2t$ value	$\int i^2 dt$	$T_C = 25\text{ °C}$ , $t_p = 10\text{ ms}$	0.5	A <sup>2</sup> s
		$T_C = 160\text{ °C}$ , $t_p = 10\text{ ms}$	0.3	
Power dissipation	$P_{tot}$	$T_C = 25\text{ °C}$	42	W
Operating and storage temperature	$T_j, T_{stg}$		-55 to 175	°C

### Electrical Characteristics at $T_j = 175\text{ °C}$ , unless otherwise specified

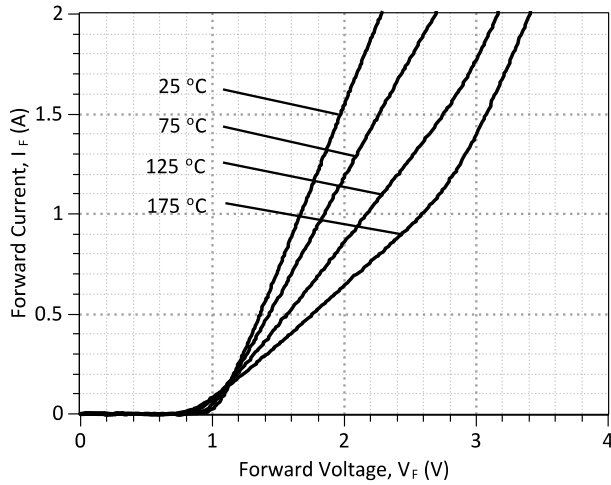
Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Diode forward voltage	$V_F$	$I_F = 1\text{ A}$ , $T_j = 25\text{ °C}$	1.50	1.56	1.75	V
		$I_F = 1\text{ A}$ , $T_j = 175\text{ °C}$	2.29	2.39	3.68	
Reverse current	$I_R$	$V_R = 1200\text{ V}$ , $T_j = 25\text{ °C}$	0.2	0.4	4.5	$\mu\text{A}$
		$V_R = 1200\text{ V}$ , $T_j = 175\text{ °C}$	0.5	1.0	11.3	
Total capacitive charge	$Q_C$	$I_F \leq I_{F,MAX}$ $di_F/dt = 200\text{ A}/\mu\text{s}$ $T_j = 175\text{ °C}$	$V_R = 400\text{ V}$	7	nC	
Switching time	$t_s$		$V_R = 960\text{ V}$	13		
		Total capacitance	$C$	$V_R = 400\text{ V}$	< 17	ns
$V_R = 960\text{ V}$						
$V_R = 1\text{ V}$ , $f = 1\text{ MHz}$ , $T_j = 25\text{ °C}$	69					
Total capacitance	$C$	$V_R = 400\text{ V}$ , $f = 1\text{ MHz}$ , $T_j = 25\text{ °C}$	10	pF		
		$V_R = 1000\text{ V}$ , $f = 1\text{ MHz}$ , $T_j = 25\text{ °C}$	8			

### Thermal Characteristics

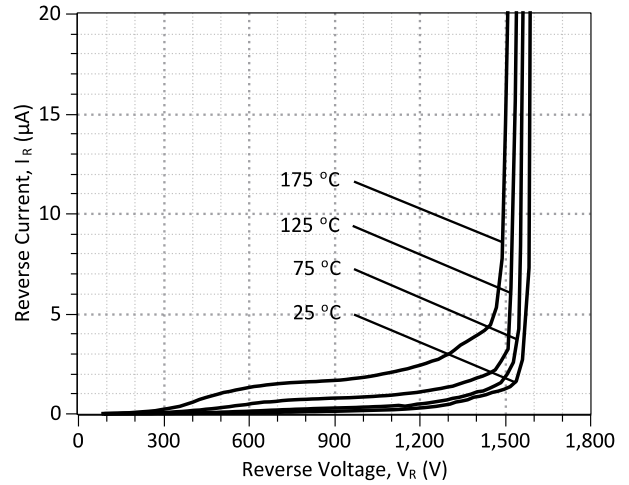
Thermal resistance, junction - case	$R_{thJC}$	3.6	°C/W
-------------------------------------	------------	-----	------

### Mechanical Properties

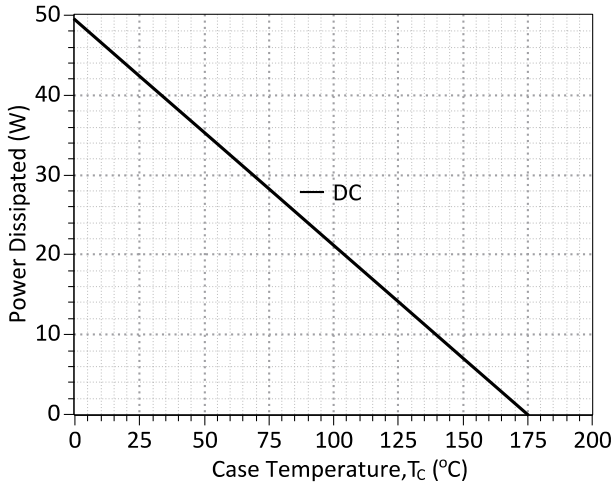
Mounting torque	M	0.6	Nm
-----------------	---	-----	----



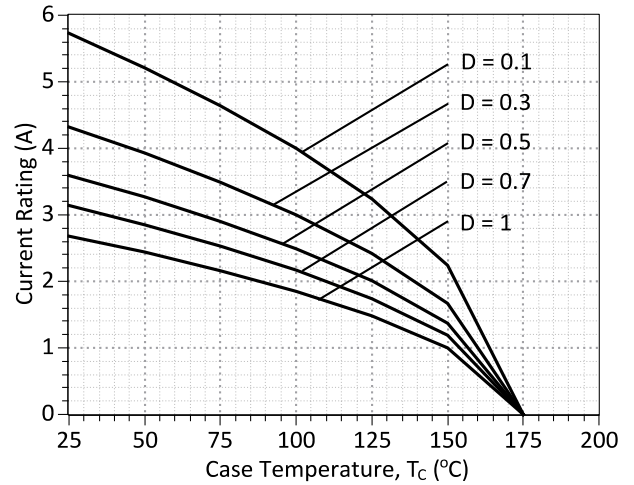
**Figure 1: Typical Forward Characteristics**



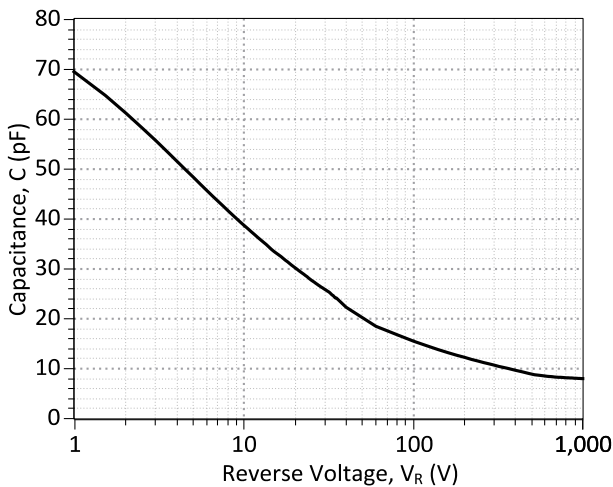
**Figure 2: Typical Reverse Characteristics**



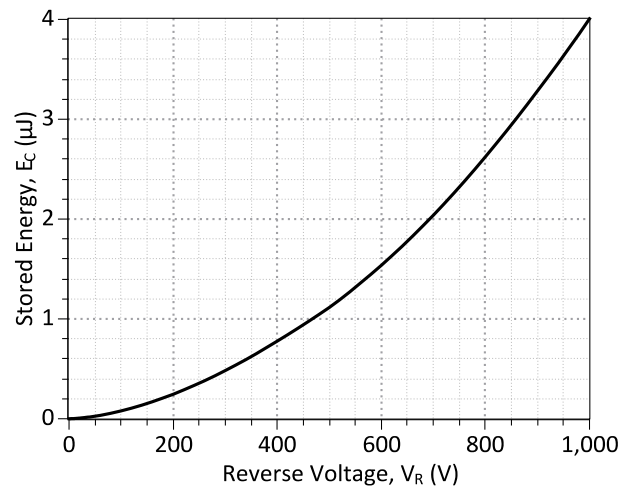
**Figure 3: Power Derating Curve**



**Figure 4: Current Derating Curves (D =  $t_p/T$ ,  $t_p = 400 \mu s$ )  
(Considering worst case  $Z_{th}$  conditions)**



**Figure 5: Typical Junction Capacitance vs Reverse Voltage Characteristics**



**Figure 6: Typical Switching Energy vs Reverse Voltage Characteristics**

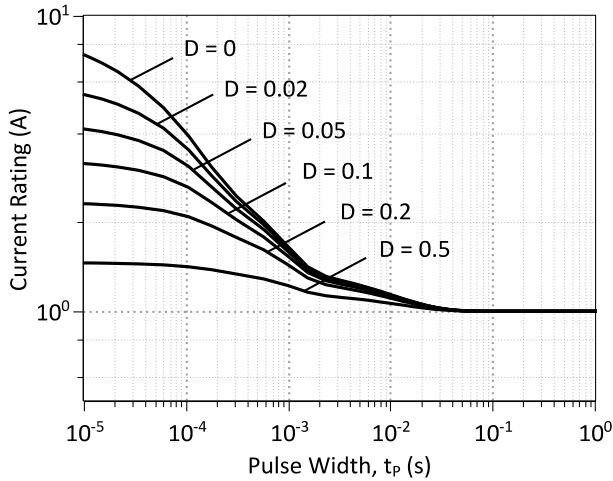


Figure 7: Current vs Pulse Duration Curves at  $T_c = 160\text{ }^\circ\text{C}$

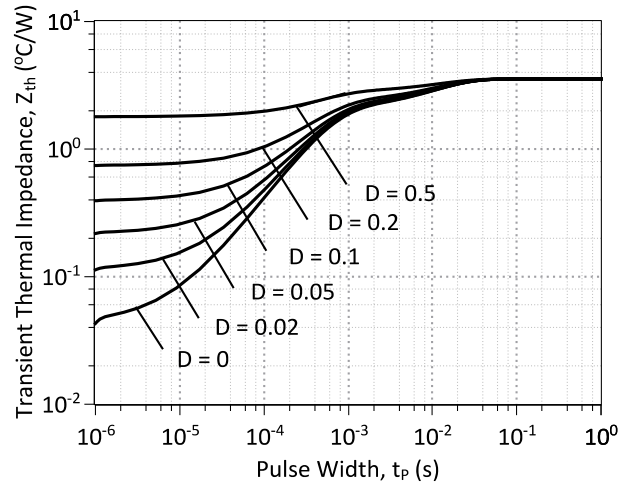
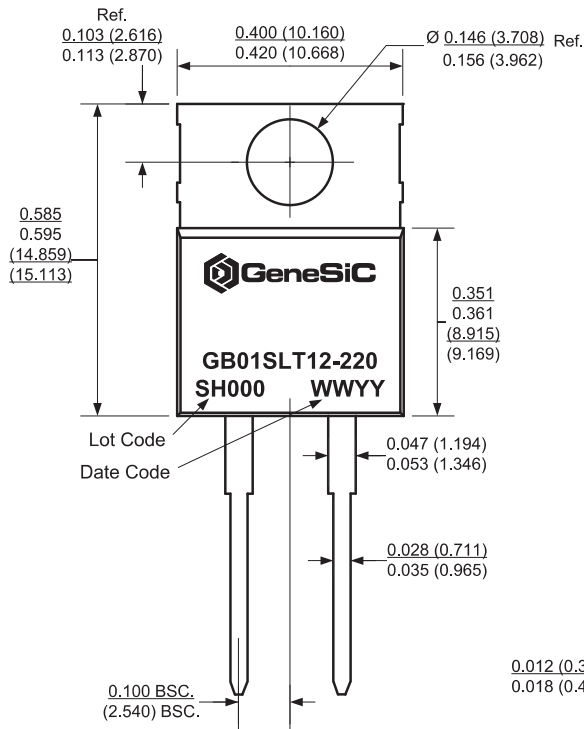


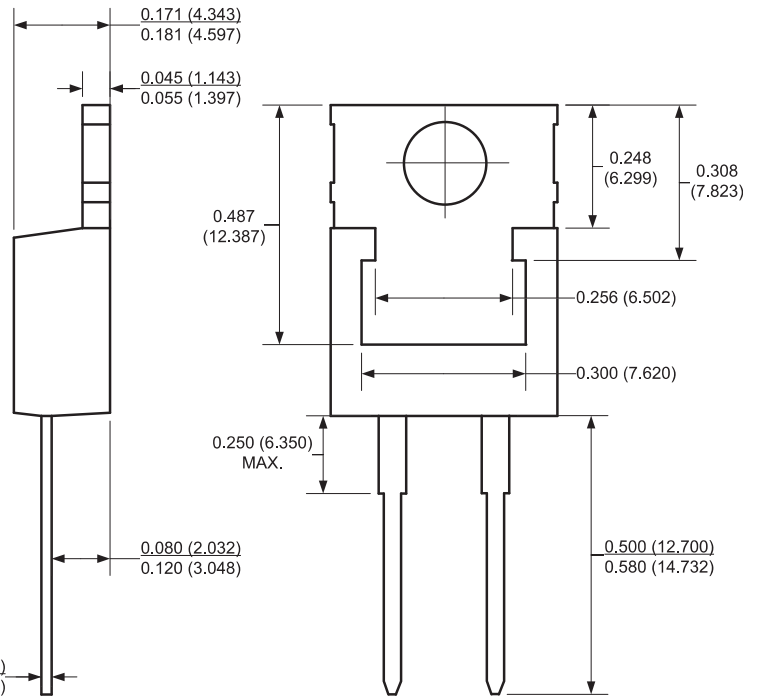
Figure 8: Transient Thermal Impedance

**Package Dimensions:**

**TO-220AC**



**PACKAGE OUTLINE**



**NOTE**

1. CONTROLLED DIMENSION IS INCH. DIMENSION IN BRACKET IS MILLIMETER.
2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS

<b>Revision History</b>			
Date	Revision	Comments	Supersedes
2013/02/05	2	Second generation update	
2012/05/22	1	Second generation release	
2010/12/13	0	Initial release	

Published by

GeneSiC Semiconductor, Inc.  
43670 Trade Center Place Suite 155  
Dulles, VA 20166

GeneSiC Semiconductor, Inc. reserves right to make changes to the product specifications and data in this document without notice.

GeneSiC disclaims all and any warranty and liability arising out of use or application of any product. No license, express or implied to any intellectual property rights is granted by this document.

Unless otherwise expressly indicated, GeneSiC products are not designed, tested or authorized for use in life-saving, medical, aircraft navigation, communication, air traffic control and weapons systems, nor in applications where their failure may result in death, personal injury and/or property damage.